

AD-HOC MESSAGE

Another new material for the 3D-MID process

Ticona GmbH and LPKF AG sign know-how and licence agreement

A know-how and licence agreement has been closed for the material Vectra[®] LCP (Liquid Crystal Polymer). This agreement enables the Ticona GmbH to modify their LCP material for the LPKF-LDS process to produce 3D-MID circuits. This plastic allows the production of ultra-fine mechanical 3D structures by injection moulding, which in connection with the laser structuring of circuits is a unique feature worldwide. The circuit structures on this material are solderable due to the high temperature resistance of the LCP material. Possible applications are e.g. within the field of hearing aids, mobile communication devices and sensor technology for automobile electronics.

This new contract will again positively influence LPKF's chances to establish this technology and to sell 3D-MID laser systems in the coming years.